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Example of table or graphic and caption in a paper:

Table 2. Cu Dissolution DOE Matrix

Exp. #	ALLOY	Contact Time Replicates (secs)					
		1	2	3	4	5	6
1-1	Sn-Pb	30	30	30	30	30	30
		50	50	50	50	50	50
1-2	SAC405	30	30	30	30	30	30
		50	50	50	50	50	50
1-3	SAC305	30	30	30	30	30	30
		50	50	50	50	50	50
1-4	Sn-Cu + Ni (1)	30	30	30	30	30	30
		50	50	50	50	50	50
2-1	Sn-Ag-Cu + Bi	30	30	30	30	30	30
		50	50	50	50	50	50
2-2	Sn-Ag-Cu + Sb	30	30	30	30	30	30
		50	50	50	50	50	50
2-3	Sn-Cu + X/Y	30	30	30	30	30	30
		50	50	50	50	50	50
2-4	Sn-Cu + Ni (2)	30	30	30	30	30	30
		50	50	50	50	50	50
DOE RUNS		16	16	16	16	16	16
TOTAL DOE RUNS		96					

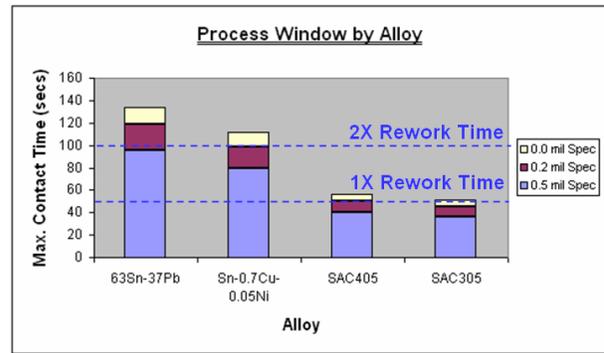


Figure 1. PTH Process Window by Alloy

EXAMPLE of placement of a table (or graphic) that will not fit in one column.

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The third development stage was to build the actual notebook or desktop production motherboard in a lead-free configuration and perform the full battery of board level and system level testing. One notable discovery in this stage was that torsion testing of a notebook motherboard could result in PCB pad cratering due to strain from the high modulus SAC alloy; this was consistent with work from others [6]. As a result some BGA components on notebook products required partial underfilling (or edge glue) to prevent such failures. Such techniques are now fairly common for lead-free assemblies [7]. Without getting into great detail, it can be said that in the course of this extensive two year effort many lead-free issues were discovered and each was resolved prior to launching of the consumer lead-free products.

Since 2005 many tens of millions of lead-free products have been produced and field results show the reliability to be as good (and in many cases better) than the leaded products they replaced. However, one issue did escape this qualification process. Over time it was discovered by Dell [8] and others [9, 10, 14] that the immersion silver surface finish selected for lead-free PCBs had the susceptibility to creep corrode when used in high sulfur and high humidity environments. An IPC investigation is currently underway to develop test methods to better predict sulfur based corrosive environments, while silver manufacturers are actively working to improve their ImAg surface finishes. However, until such time that ImAg is proven to not creep corrode, Dell will not employ this surface finish for critical business products that may be exposed to such harsh

Table 1. Differences in a lead-free server compared to transitioning lead-free client products.

Change/Challenge	Risk	Action
PCB thickness increase (from 0.062" to 0.092 or greater)	Incomplete hole fill in wave	Improve wetting with flux, alloy choice, and/or increase temp
	Increased thermal stress on PTHs	Ensure PTH components can survive increased temp
1-3 additional processor sockets are required per board.	More thermal energy needed to achieve consistent solder joints can cause heat damage.	Reduce z-axis CTE and/or increase Cu thickness.
All boards require 2 side SMT + wave solder.	Solderability of PTH degrades with 2 nd side reflow	Ensure surface finish has good solderability and PCB can handle added heat stress.
In circuit test strain limits could be larger with thicker boards.	ICT stress must be minimal to prevent BGA fracture	Ensure a robust surface finish that remains solderable after 2 heat cycles.
Immersion silver surface finish eliminated due to corrosion risk	Alternative finish must meet ICT and solderability requirements	Ensure low contact resistance on test points.
PCB laminate may change from what was used on DT and NB products.	Thermal cycle life of the BGA components can change	Investigate several alternatives (OSP, ImSn, ENIG, and LF HASL)
Larger and heavier assemblies	Shock/vibration differences	Build test vehicle and run thermal cycle testing
PTH rework time is longer	Cu dissolution can reduce knee thickness below specification.	Test final assemblies using shock/vibration/HALT
		Select rework alloy and optimize process to reduce copper dissolution

environments (this would include server products).

DISCUSSION OF CHALLENGES

All of this previous experience with converting notebook and desktop products to lead-free was leveraged in taking the next step of converting the complex and challenging class A server products to lead-free. An effective way to start with implementation of any major product or manufacturing change is to consider all the differences from what was previously known and the impact these differences may have on the final product. In this case the primary gaps in transitioning from a lead-free consumer product to a lead-free server are shown in Table 1.

It is also helpful to understand any constraints that may exist. Some constraints at Dell's EMs include the fact that nitrogen reflow was not widely available and no-clean solder flux was required. Without a nitrogen blanket one can expect heavier oxidation of the surfaces to be soldered. In addition, the no-clean fluxes are not as active as the water soluble fluxes, therefore reducing the oxides is more difficult. Another constraint is to ensure that all IPC 610D solder joint inspection criteria are met (some papers have been written that suggest that hole fill requirements could be reduced while still maintaining sufficient reliability [11] but there is insufficient data at this time to support such a change in specifications). A further constraint is that components with ball pitch as low as 0.8 mm and peripheral

HAVE HIGH Cu DISSOLUTION RATES OF SAC305/405 ALLOYS FORCED A CHANGE IN THE LEAD FREE ALLOY USED DURING PTH PROCESSES?

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ABSTRACT

To date, the majority of the Electronics Manufacturing industry has implemented either SAC305 or 405 alloys to manufacture Pb-free (E.U. RoHS, compliant) products, for both the SMT and PTH card assembly processes. This original alloy composition choice, dating back to 1999, was based on early research into the metallurgy and reliability of the alloy/s and agreement amongst top companies involved in iNEMI, JEITA and within the European Union. A recent shift towards SAC305 has recently been observed within the industry due to its lower cost when compared to SAC405, based on lower silver content. Historically, reliability assessment efforts have focused on SMT solder joint connections as PTH solder joint connections were not typically a reliability concern due to their construction. Conceptually, it is easier from a process and supply chain point of view to use a single Pb-free alloy for both the SMT and PTH attach process. However, issues relating to high rates of copper (Cu) dissolution occurring during the PTH rework process using either SAC305 or 405 alloys may force a change in this concept.

The high Cu dissolution rates experienced when using SAC305/405 may dictate a change in the Pb-free alloy used during the PTH rework process, in order for typical methods of rework (i.e. solder fountain) to continue to be used.

However, making a change in the Pb-free alloy used for only the PTH rework process itself creates new questions which would need to be answered. For instance, what is the impact of reworking a SAC305/405 assembled connector using an alternate Pb-free alloy? Is changing the Pb-free alloy used within the primary attach process to match the PTH rework alloy the right solution? This leads to further questions relating to process controls and reliability of a final "mixed" Pb-free joint as well as the "pure" alternative Pb-free alloy selected which would need to be addressed.

This paper discusses the work performed studying and comparing the Cu dissolution rates of various Pb-free alloys available on the market today. Although the use of a PCB with a nickel plated layer can reduce the occurrence of Cu dissolution, all experiments in this study were performed on an OSP finished board. Finishes such as OSP which do not have a nickel layer represent the worst case scenario with respect to Cu dissolution. An OEM server product was used as the test vehicle throughout this study. A total of six Pb-free alloys and a eutectic tin/lead (Sn-Pb) control alloy were included in the evaluation. Specifically, two binary eutectic and four ternary "near eutectic" Pb-free alloys were included. Each of the "alternative Pb-free alloys" studied include varying levels of certain elemental additives. Common additives included in some of these alloys are,

Specifically, the knee of the PTH barrel will dissolve at a faster rate as compared to the annular ring and/or barrel wall⁵. This is explained by atomic diffusion theory correlating the effects of surface geometry on the rate of atomic diffusion, as well as proximity to the solder flow. The main reason for the variance across a connector has been linked to flow rate. Typical flow-well design utilizes a single central opening through which solder can flow. This design point often results in higher dissolution rates within center barrels of a connector rework location. Center pins are often subjected to turbulent solder flow, while edge pins are subjected to laminar flow. Modifications in flow-well design have proven effective in reducing solder turbulence, resulting in reduced Cu dissolution rates during solder fountain rework⁶.

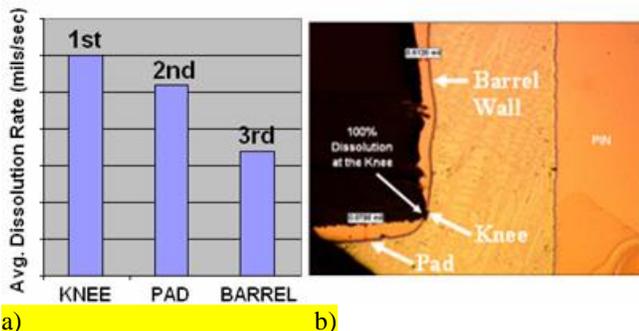


Figure 2. a) Cu dissolution rates by barrel geometry ; b) X-section showing 100% Cu dissolution at the knee location.

METALLURGICAL THEORY

All of the “alternative Pb-free alloys” included in this study are primarily Sn-Ag-Cu or Sn-Cu based alloys with some controlled levels of additives. It is the addition of these additives which help to control the final grain structure thus improving final joint appearance, wetting, and flow characteristics. Resultant effects include improved barrel fill and reduced Cu dissolution. The type, wt% and combination of the base elements and additives all have an impact on controlling the above properties. This section will provide a summary on the impact of each of the common additives, specifically on effecting Cu dissolution from a metallurgical point of view.

Kinetics of Cu Dissolution

Before being able to discuss the impact of each of the additives on Cu dissolution, the basic mechanisms behind how Cu dissolution occurs need to be explained.

The Cu dissolution process itself can be considered as occurring by the following mechanisms⁷:

- (1) Departure of atoms of the solid surface and
- (2) Diffusion into the solder melt.

Diffusion controlled processes result in a uniform attack while interface controlled reactions may be recognized by preferential etching of grain boundaries. In this study smooth copper/intermetallic interface without any signs of

grain boundary attack was detected. The mechanisms themselves occur in series and the slowest one determines the overall kinetics of the process. The most general dissolution rate equation is shown below⁸:

$$C = C_s(1 - \exp(-K(A/V)t))$$

Where C is the solute concentration at time t , K is the solution rate constant and V is the volume of liquid. This equation can be applied for diffusion controlled or interface controlled processes. The solution rate constant K is D/δ for the case of diffusion control, where D is the diffusion coefficient in liquid and δ is the thickness of the effective concentration boundary layer. In general, the boundary layer thickness is less than 0.1mm. This boundary layer is a layer of liquid existing immediately adjacent to the solid copper (Cu) interface/intermetallic layer (Figure 3). The Cu concentration gradient exists within this layer. During the diffusion controlled process the liquid boundary layer which is formed during the solder fountain rework is an important feature of Cu dissolution.

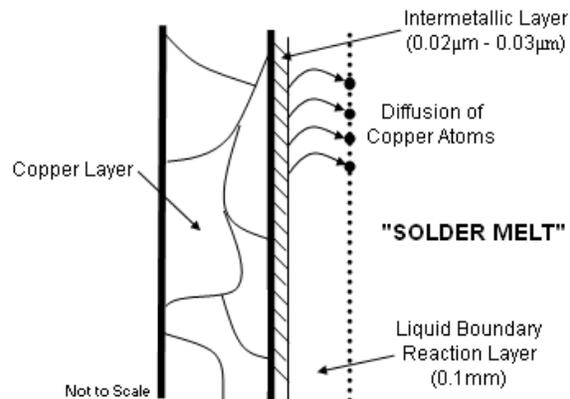


Figure 3. Departure and Diffusion of Cu Atoms into Solder Melt (Kinetics of Cu Dissolution)

The thickness of this liquid diffusion boundary layer is a function of the physical properties, the velocity of the solution and the diffusion coefficient. The dissolution rate increases with increasing peripheral velocity, which is relevant to the fountain rework situation. Other influences in reducing Cu dissolution would be based on the type of additive present in the bulk solder. The exact influence of each will be discussed below.

Sn-Pb and Sn-Ag-Cu and Sn-Cu Based Alloys

It has been found that it is the Sn component of most solders that reacts with the copper substrate⁹. In the case of Sn-Pb solders, only the Sn components react, since Cu is nearly insoluble in liquid Pb at soldering temperatures and forms no intermetallic compounds with it. Therefore, the Sn-rich solders dissolve more Cu than eutectic Sn-Pb solder.

With increasing copper concentration in the solder the rate of dissolution decreases because of the concentration gradient reduction. Thus, solders with 0.7% Cu remove less copper from the plating layer than solders with 0.5% Cu.

Therefore, based on this, the Cu dissolution rates of the SAC305 alloy (0.5%Cu) should be greater than that of the SAC405 alloy (0.7%Cu). This will be further illustrated in the results section.

Effect of Additives

An effect of a reactive third and fourth component within a binary and ternary based alloy respectively is not properly understood yet and cannot be predicted without experimentation under different conditions. Below is brief summary of the expected reaction of common additives specifically with respect to controlling Cu dissolution.

1. Some components such as Sb and Bi may dilute the Sn-rich solder and reduce Cu dissolution in molten solder. Typically these elements improve solder grain structure, strength and/or ductility. However they are prone to defects such as fillet lifting and contamination issues.

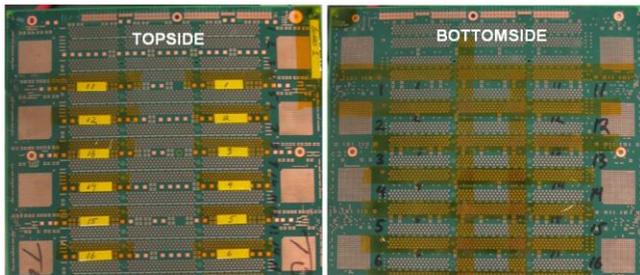


Figure 5. Sample Preparation

Each DOE sample was cross-sectioned along the entire length of the sample at a middle row and Cu thickness measurements taken. Cu thickness measurements were focused solely at the knee location (Figure 6). In absence of a current IPC industry specification for remaining Cu plating thickness after rework, an OEM specification of 0.5 mils of remaining Cu plating was used¹⁴.

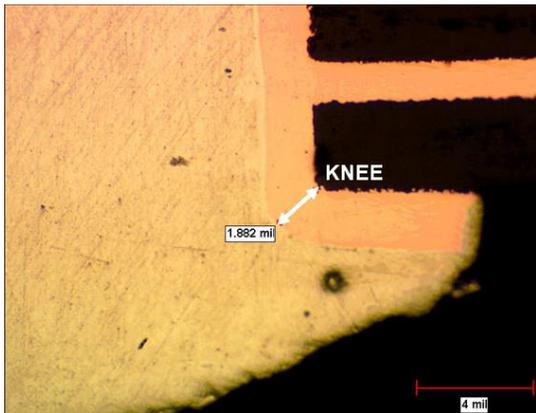


Figure 6. Cu Thickness Measurement Locations

EXPERIMENTAL RESULTS

The statistical results indicate that both contact time as well as alloy type have a significant impact on the rate of Cu dissolution (Table 4).

Table 4. ANOVA Statistical Results Showing Significance of Contact Time and Alloy

Analysis of Variance for min_knee (mils), using Adjusted SS for Tests							
Source	DF	Seq SS	Adj SS	Adj MS	F	P	
Contact Time (secs)	1	1.70428	1.61816	1.61816	28.10	0.000	
Alloy Coded	6	6.08388	5.98639	0.99773	17.33	0.000	
Contact Time (secs)*Alloy Coded	6	0.56246	0.56246	0.09374	1.63	0.164	
Error	41	2.36102	2.36102	0.05759			
Total	54	10.71163					

The interaction plot (Figure 7), illustrates the Cu dissolution results of each alloy at both 30 and 50 second exposure times. The values on the y-axis are the measured remaining Cu thickness of the knee plating after a 30 and 50 second exposure to molten solder (x-axis). The alternative Pb-free alloys have been coded (Alloy A, B, C and D) with the results of SAC305, 405 as well as the Sn-Pb control cell identified in the chart.

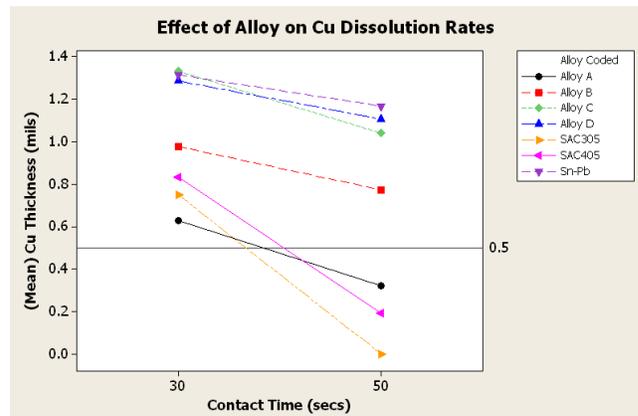


Figure 7. Interaction Plot Results – Effect of Alloy on Cu Dissolution Rates

The results show that two of the alternative Pb-free alloys performed the best with respect to the rate of Cu dissolution occurring. Specifically, Alloy C and D results are comparable to those of the Sn-Pb control cell. In addition, Alloy B's result also showed a statistically significant difference from the performance of SAC305/405 alloys and although showing poorer results, it had no statistical difference compared to Alloys C, D and the Sn-Pb cell. Although it had a similar slope to the other alternative Pb-free alloys, Alloy A showed a slightly higher occurrence of Cu dissolution at the exposure times of 30 and 50 seconds. Alloy A has a statistically similar rate of dissolution compared to the SAC305/405 alloys. It can be seen from Figure 7 that Alloy A's results drops below the specification limit of 0.5 mils of remaining Cu plating at approximately 40 seconds, which is a concern.

As the Pb-free PTH process window is strongly dependant on total cumulative exposure to solder, the final Cu dissolution rates calculated can be correlated to a maximum expected allowable process window for each alloy studied. Figure 8 illustrates each alloy's process window using three different specification limits of remaining Cu plating thickness for comparison sake. Also illustrated on the graph is the total time required to 1X (50 seconds) and 2X (100

seconds) rework the DIMM connector assembled on the same test vehicle. Based on this, it can be seen that both Alloy C and D are capable of performing up to a 2X rework using any of the three specification limits listed. Alloy B is capable of performing a 1X rework using any of the three specification limits, however falls short of being able to complete a 2X rework. Finally, Alloy A along with SAC305 and 405 are capable of performing a 1X rework, however, only when using a specification limit of 0.2mils of remaining Cu or less. All three are incapable of completing a 2X PTH rework.

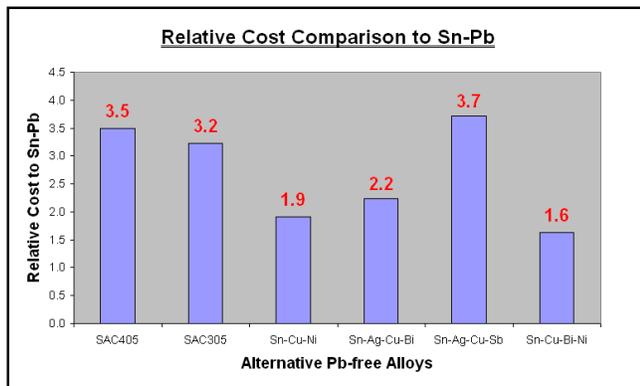


Figure 16. Relative Cost of Alloy Compared to Sn-Pb

CONCLUSIONS

The high Cu dissolution rates of SAC305/405 alloys are indeed the main driving factor in the requirement to change the Pb-free alloy used within the solder fountain rework process. This change could also potentially drive a change in the alloy used within the wave solder attach process in order to simplify the manufacturing process and reduce the degree of pot contamination during PTH rework. However the push to replace SAC305/405 alloy with an alternative Pb-free alloy within the wave soldering process could easily be justified from a financial perspective in addition to technical justifications. Some of the alternative Pb-free alloys offer a 50% reduction in cost compared to SAC305/405 alloys, which can be quite significant if this saving is shared amongst multiple wave soldering machines.

This study indicated that there are three "alternative Pb-free alloys" (B, C and D) which could be used as potential replacements for the SAC305/405 alloy based on their Cu dissolution rate results. Each of the three alloys showed statistically similar dissolution rates to that of the Sn-Pb alloy. There are however, other considerations aside from Cu dissolution rates which need to be considered before selecting an appropriate alternative alloy. These include, the final joint quality produced as well as the reliability. In addition, supply chain considerations, logistics and costs are important factors in selecting a replacement Pb-free alloy.

FUTURE WORK

Future work will include performing forced PTH reworks (1X and 2X) and reliability studies including ATC and mechanical testing to further understand the impact of Cu

dissolution on PCB reliability. This will include both pure and mixed Pb-free conditions using the top three alternative Pb-free alloys from this study. There is a large amount of data available on solder joint reliability using SAC305/405 alloy, but further testing will be required if an alternative Pb-free alloy is chosen for PTH processes, especially primary attach. Provide recommendations to include specific IPC specifications relating to remaining Cu plating due to Cu dissolution post PTH rework. In addition, steps required to implement an alternative Pb-free alloy into the manufacturing process will be taken such as performing initial validation by applying the development findings to controlled volume manufacturing conditions.

ACKNOWLEDGEMENTS (Optional)

The authors would like to thank each of the solder suppliers who were involved in supporting this study. The authors would also like to acknowledge the support of IBM in this study, in particular Jim Wilcox and Jim Bielick. In addition, thank you to Celestica's support throughout this study, in particular to Linda Scala, Thilo Sack, Irene Sterian, John McMahon, Marianne Romansky, Heather McCormick and Jeffrey Kennedy

REFERENCES

- [1] R.N. Wild, Proceedings of International NEPCON Conference, Briton, 1971, pp.81.
- [2] J.R. Getten and R. Senger, IBM J. Res. Dev., V.26, 1982, pp.379.
- [3] C. Hamilton, P. Snugovsky, Ph.D., Celestica, M. Kelly, IBM "A Study of Copper Dissolution during Pb-free PTH Rework using a Thermally Massive Test Vehicle", Proceedings of SMTA International, September 2006.
- [4] F. Boyle, D. Jean, Plexus, D. Lee, Boston Scientific "A Study of Copper Dissolution in Pb-Free Solder Fountain Systems", Proceedings of SMTA International, September 2006.
- [5] C. Hamilton, Celestica, "A Study of Copper Dissolution during Pb-free PTH Rework", Proceedings of International Conference on Lead-free Soldering (CMAP), May 2006.
- [6] C. Hamilton, Celestica, "Laminar Flow-well", Patent Pending, May 2006.
- [7] N.J. Hoffman, I. Minkoff, "The Isothermal Corrosion ($\alpha + \beta$) Ni-Sn Alloys in Pure Liquid Sn Component", Proceedings of American Society for Metals and the Metallurgical Society of AIME, 1969, pp. 391
- [8] Y. Shoji, S. Uchida, T. Ariga, "Dissolution of Solid Copper Cylinder in Molten Tin-Lead Alloys under Dynamic Conditions", Proceedings of American Society for Metals and the Metallurgical Society of AIME, 1982, pp. 441.
- [9] ...